ABSTRACT

[0036] A Wire Bonder is designed in such a way and equipped with the appropriate means so that in production the current bond cycle is completed in all possible cases such as interruption of the electrical power supply, failure of the compressed air, failure of the vacuum, actuation of the emergency switch, triggering a stop signal caused by the response of a safety mechanism. A bond cycle is to be understood as one single bonding process with which the bond wire is attached to a connection point of the semiconductor chip, formed into a wire loop and attached to a connecting point of the substrate and with which the wire is then torn away from the finished wedge bond.